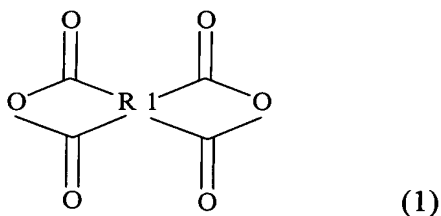


IN THE CLAIMS

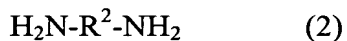
Please amend the claims as follows:

Claim 1 (Currently Amended) A method of forming a cavity between multilayered wirings, comprising:

coating the surface of a first dielectric film formed on a semiconductor substrate with a polyamic acid and/or a polyimide obtained from at least one alicyclic tetracarboxylic acid dianhydride represented by the following general formula (1) and at least one alicyclic diamine represented by the following general formula (2):



wherein R¹ represents a tetravalent alicyclic hydrocarbon group having 4-20 carbon atoms, the tetravalent alicyclic hydrocarbon group being able to contain a cyclic ether structure in the molecule, and



wherein R² represents a divalent alicyclic hydrocarbon group having 4-20 carbon atoms,

patterning the polyamic acid and/or the polyimide as a cavity-forming polymer,
embedding a metal in a pattern in the cavity-forming polymer to form a metallic wiring layer,

forming a second dielectric film on the cavity-forming polymer containing the embedded metal ~~a metallic wiring~~, and

removing the cavity-forming polymer ~~between~~ present in the multilayered wirings
wiring layer by heating to form a cavity ~~between the metallic wirings~~.

Claim 2 (Original) The method as claimed in claim 1, wherein the polyamic acid and/or the polyimide has a weight average molecular weight, as reduced into polystyrene, in the range of 1,000-500,000.

Claim 3 (Original) The method as claimed in claim 1, wherein the polyamic acid and/or the polyimide has a weight loss on heating at 350°C for one hour in an inert gas atmosphere and/or a vacuum atmosphere of 5% by weight or less and a weight loss on heating at 500°C for one hour in an inert gas atmosphere and/or a vacuum atmosphere of 80% by weight or more.

Claim 4 (Original) The method as claimed in claim 1, wherein the polyamic acid and/or the polyimide has a glass transition temperature of 200°C or higher.

Claim 5 (Original) The method as claimed in claim 1, wherein the polyamic acid and/or the polyimide has an elastic modulus at 25°C of 5 GPa or more.

Claim 6 (Previously Presented) The method as claimed in claim 1, wherein said alicyclic tetracarboxylic acid dianhydride represented by the general formula (1) is 4,10-dioxatricyclo[6.3.1.0^{2,7}]-dodecane- 3,5,9,11-tetraone.

Claim 7 (Previously Presented) The method as claimed in claim 1, wherein said alicyclic diamine represented by the general formula (2) is a member selected from the group consisting of 1,3-diaminocyclohexane, 1,4-diaminocyclohexane, 1,2-bisaminomethylcyclohexane, 1,3-bisaminomethylcyclohexane, 1,4-bisaminomethylcyclohexane, isophoronediamine, 4,4'-diaminobiscyclohexyl, 3,3'-diaminobiscyclohexyl, bis(4-aminocyclohexyl)methane, bis(3-aminocyclohexyl)methane, 2,6-diamino-dicyclo[2.2.1]heptane, 2,5-diamino-dicyclo[2.2.1]heptane, 2,3-bis(aminomethyl)-dicyclo[2.2.1]heptane, 2,5-bis(aminomethyl)-dicyclo[2.2.1]heptane, 2,6-bis(aminomethyl)-dicyclo[2.2.1]heptane, 3,9-bis(aminomethyl)-tricyclo[6.2.1.0^{2,6}]decane, 4,9-bis(aminomethyl)-tricyclo[6.2.1.0^{2,6}]decane, 5,9-bis(aminomethyl)-tricyclo[6.2.1.0^{2,6}]decane, 1,3-diaminoadamantane, or 1,3-bis(aminomethyl)adamantane and mixtures thereof.

Claim 8 (Previously Presented) The method as claimed in claim 1, wherein said aliphatic tetracarboxylic acid dianhydride represented by the general formula (1) and said alicyclic diamine represented by the general formula (2) are reacted in an aprotic polar solvent and/or a phenol based solvent in a solids concentration of 1-30 % by weight at a temperature in the range of 0-150°C for 1-24 hours, to obtain a polyamic acid solution.

Claim 9 (Previously Presented) The method as claimed in claim 8, further comprising:

adding a dehydrating agent in an amount of 1-20 moles per mole of the aliphatic tetracarboxylic acid dianhydride represented by the general formula (1).

Claim 10 (Previously Presented) The method as claimed in claim 8, further comprising:

adding an imidation catalyst in an amount of 0.5-30 moles per mole of the aliphatic tetracarboxylic acid dianhydride represented by the general formula (1).

Claim 11 (Previously Presented) The method as claimed in claim 8, wherein said aprotic polar solvent is selected from the group consisting of γ -butyrolactone, cyclohexanone, N-methyl-2- pyrrolidone, N,N-dimethylacetamide, N,N-dimethylformamide, dimethyl sulfoxide, tetramethylurea, hexamethyl sulfonamide and mixtures thereof.

Claim 12 (Previously Presented) The method as claimed in claim 8, wherein said phenol based solvent is selected from the group consisting of m-cresol, xylenol, phenol, halogenated phenols and mixtures thereof.

Claim 13 (Previously Presented) The method as claimed in claim 1, wherein said alicyclic tetracarboxylic acid dianhydride represented by the general formula (1) and said alicyclic diamine represented by the general formula (2) are used in a proportion so that an amount of the acid anhydride group in the alicyclic tetracarboxylic acid anhydride is 0.2-2 equivalents to one equivalent of the amino group in the alicyclic diamine compound.

Claim 14 (Previously Presented) The method as claimed in claim 9, wherein said dehydrating agent is selected from the group consisting of acetic anhydride, propionic anhydride, trifluoroacetic anhydride and mixtures thereof.

Claim 15 (Previously Presented) The method as claimed in claim 9, wherein said imidation catalyst is a tertiary amine that can be dissolved or dispersed in the aprotic polar solvent and/or phenol based solvent.

Claim 16 (Previously Presented) The method as claimed in claim 9, wherein said imidation catalyst is an aliphatic tertiary amine selected from the group consisting of trimethylamine, triethylamine, tripropylamine, tributylamine and mixtures thereof.

Claim 17 (Previously Presented) The method as claimed in claim 9, wherein said imidation catalyst is N,N-dimethylaniline.

Claim 18 (Previously Presented) The method as claimed in claim 9, wherein said imidation catalyst is selected from the group consisting of pyridine, 2-methylpyridine, N-methylimidazole, quinoline and mixtures thereof.

Claim 19 (Previously Presented) A semiconductor device, comprising a cavity between metallic wirings which is obtained by the method as claimed in claim 1.

BASIS FOR THE AMENDMENT

Applicants thanks Examiner Chacko for the helpful and courteous discussion of July 15, 2005. During the discussion the Examiner agreed that an amendment to Claim 1 for clarity may overcome the rejection upon a review of Applicants written response.

Claims 1-19 are active in the present application. Claim 1 has been amended for clarity. Claim 1 now recites embedding a metal in a pattern of the cavity-forming polymer recited in the claims. Support for the amendment is found on page 19, first full paragraph and in Figure 1. No new matter is believed to have been added by this amendment.